IN THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

Claim 1 (original): A ceramic heater comprising: a ceramic substrate; an insulating layer having volume resistivity higher than that of said ceramic substrate, being formed on at least a part of said ceramic substrate; and a resistance heating element formed on said insulating layer.

Claim 2 (original): The ceramic heater according to claim 1,

wherein said ceramic substrate comprises a carbide ceramic or a nitride ceramic and said insulating layer comprises an oxide ceramic.

Claim 3 (previously presented): The ceramic heater according to claim 1,

wherein the opposite side to the face where said resistance heating element is formed of said ceramic substrate is a heating face.

Claim 4 (previously presented): The ceramic heater according to claim 1,

wherein the thickness of said insulating layer is from 0.1 to 1000 μm.

Claim 5 (previously presented): The ceramic heater according to claim 1,

wherein the volume resistivity of said insulating layer is not less than 10 times larger than the volume resistivity of said ceramic substrate.

Claim 6 (currently amended): A ceramic heater comprising:

a ceramic substrate; and

a resistance heating element formed on a surface of said ceramic substrate,

wherein said ceramic substrate is warped in one direction.

Claim 7 (original): The ceramic heater according to claim 6,

wherein the warp amount of said ceramic substrate is from 10 to 100 μm.

Application No. 09/926,713
Reply to Office Action of April 18, 2003

Claim 8 (previously presented): The ceramic heater according to claim 2,

wherein the opposite side to the face where said resistance heating element is formed of said ceramic substrate is a heating face.

Claim 9 (previously presented): The ceramic heater according to claim 2,

wherein the thickness of said insulating layer is from 0.1 to 1000 μ m.

Claim 10 (previously presented): The ceramic heater according to claim 3,

wherein the thickness of said insulating layer is from 0.1 to 1000 μ m.

Claim 11 (previously presented): The ceramic heater according to claim 8,

wherein the thickness of said insulating layer is from 0.1 to 1000 μ m.

Claim 12 (previously presented): The ceramic heater according to claim 2,

wherein the volume resistivity of said insulating layer is not less than 10 times larger than the volume resistivity of said ceramic substrate.

Claim 13 (previously presented): The ceramic heater according to claim 3,

wherein the volume resistivity of said insulating layer is not less than 10 times larger than the volume resistivity of said ceramic substrate.

Claim 14 (previously presented): The ceramic heater according to claim 8,

wherein the volume resistivity of said insulating layer is not less than 10 times larger than the volume resistivity of said ceramic substrate.

Claim 15 (new): The ceramic heater according to claim 1,

wherein said resistance heating element comprises a plurality of circuits.

Claim 16 (new): The ceramic heater according to claim 1,

wherein said resistance heating element comprises at least one of a noble metal, lead, tungsten, molybdenum, nickel, and a conductive ceramic.

Claim 17 (new): The ceramic heater according to claim 1,

Application No. 09/926,713 Reply to Office Action of April 18, 2003

wherein said resistance heating element comprises a metal oxide.

Claim 18 (new): The ceramic heater according to claim 1,

wherein said ceramic substrate is capable of use at a temperature of 100°C or higher.

Claim 19 (new): The ceramic heater according to claim 1,

wherein said ceramic substrate has a thickness of 10 mm or less.

Claim 20 (new): The ceramic heater according to claim 1,

wherein said ceramic substrate has a diameter of 200 mm or more.

Claim 21 (new): The ceramic heater according to claim 1,

wherein said ceramic substrate has a diameter of 300 mm or more.

Claim 22 (new): The ceramic heater according to claim 1,

wherein said ceramic substrate comprises a bottomed hole in the bottom face of the ceramic substrate and a temperature-measuring element, and said temperature-measuring element is inserted into said bottomed hole.

Claim 23 (new): The ceramic heater according to claim 6,

wherein said resistance heating element comprises a plurality of circuits.

Claim 24 (new): The ceramic heater according to claim 6,

wherein said resistance heating element comprises at least one of a noble metal, lead, tungsten, molybdenum, nickel, and a conductive ceramic.

Claim 25 (new): The ceramic heater according to claim 6,

wherein said resistance heating element comprises a metal oxide.

Claim 26 (new): The ceramic heater according to claim 6,

wherein said ceramic substrate is capable of use at a temperature of 100°C or higher.

Claim 27 (new): The ceramic heater according to claim 6,

wherein said ceramic substrate has a thickness of 10 mm or less.

Application No. 09/926,713 Reply to Office Action of April 18, 2003

Claim 28 (new): The ceramic heater according to claim 6,

wherein said ceramic substrate has a diameter of 200 mm or more.

Claim 29 (new): The ceramic heater according to claim 6,

wherein said ceramic substrate has a diameter of 300 mm or more.

Claim 30 (new): The ceramic heater according to claim 6,

wherein said ceramic substrate comprises a bottomed hole in the bottom face of the ceramic substrate and a temperature-measuring element, and said temperature-measuring element is inserted into said bottomed hole.